



HTIF127

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HTIF127 is designed for use in general purpose amplifier and low-speed switching applications.

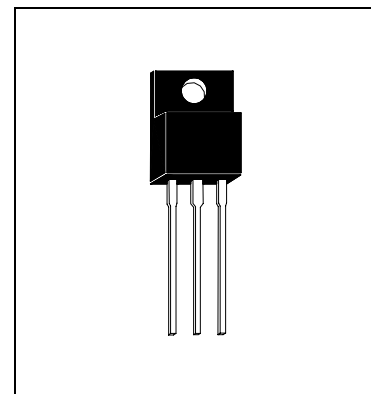
Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 45 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage -100 V
BVCEO Collector to Emitter Voltage -100 V
BVEBO Emitter to Base Voltage -5 V
IC Collector Current (Pulse)..... -8 A
IC Collector Current (Continuous)..... -5 A
IB Base Current -120 mA

Characteristics (Ta=25°C)

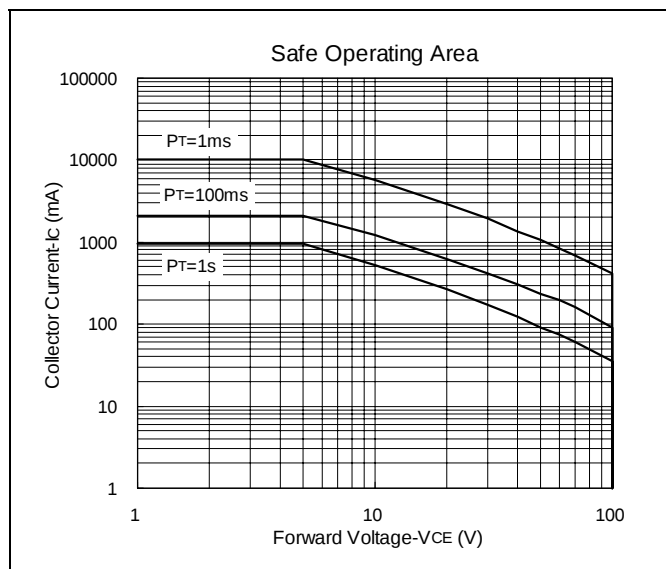
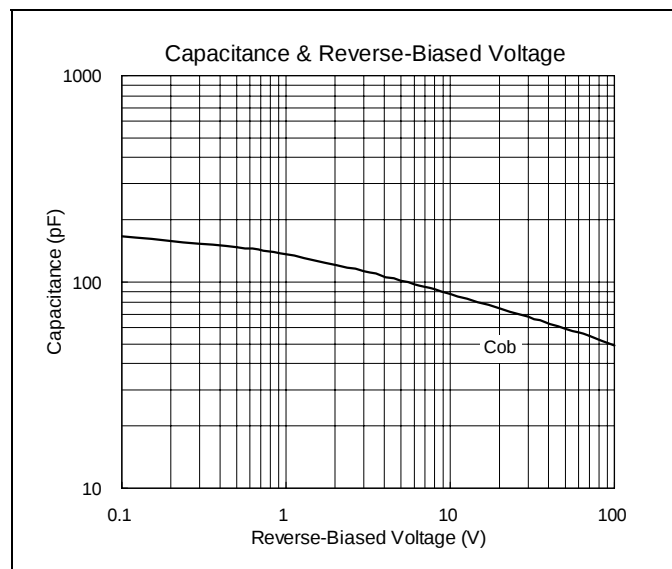
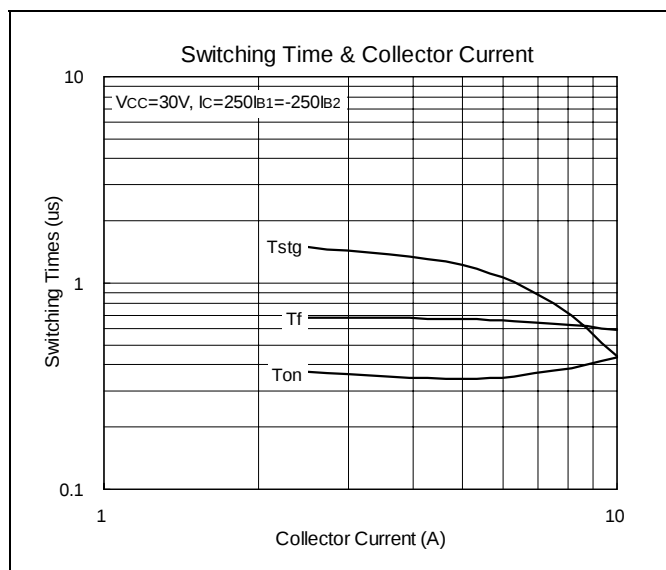
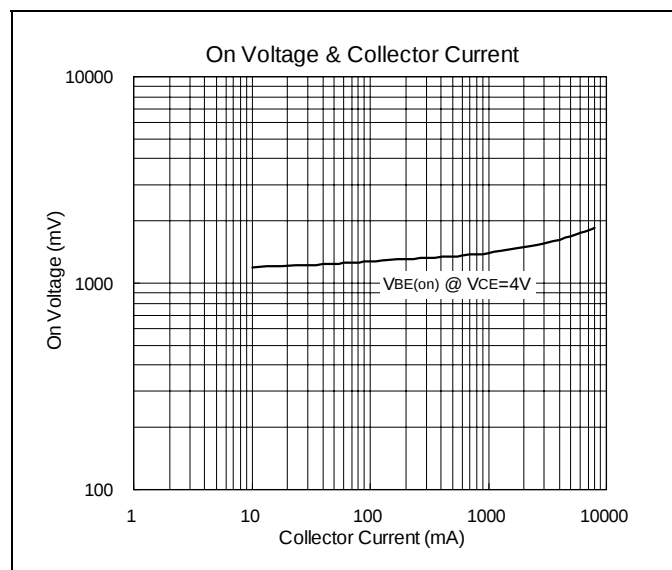
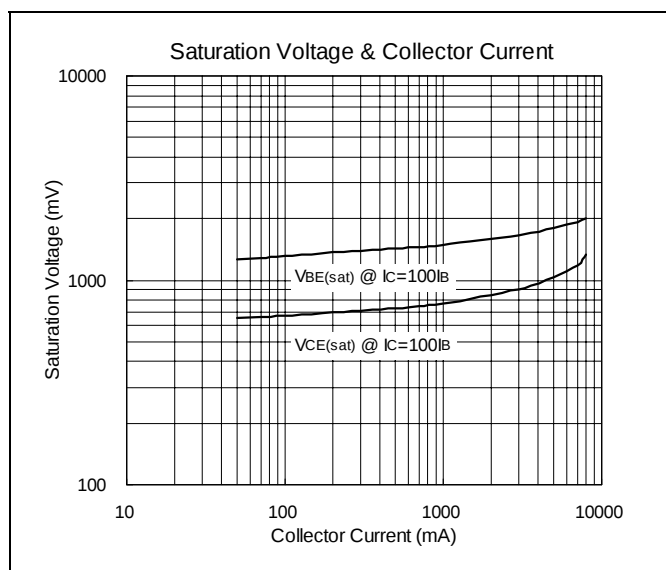
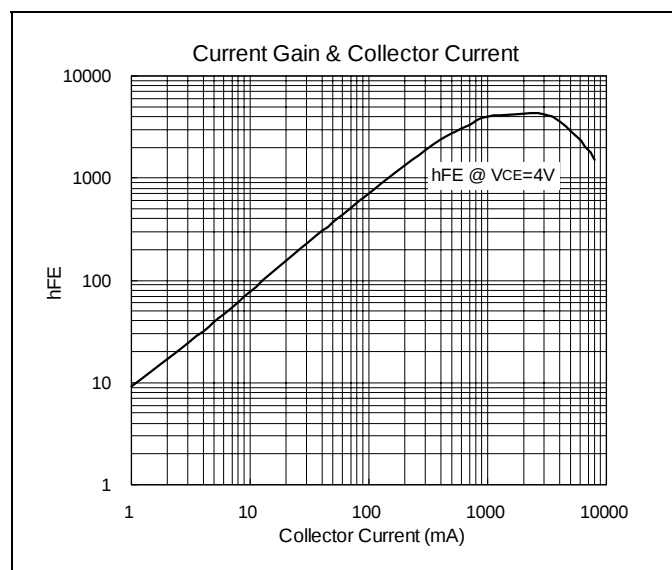
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-100	-	-	V	IC=-1mA
*BVCEO	-100	-	-	V	IC=-100mA
ICBO	-	-	-200	uA	VCB=-100V
ICEO	-	-	-500	uA	VCE=-50V
IEBO	-	-	-2	mA	VEB=-5V
*VCE(sat)1	-	-	-2	V	IC=-3A, IB=-12mA
*VCE(sat)2	-	-	-4	V	IC=-5A, IB=-20mA
*VBE(on)	-	-	-2.5	V	IC=-3A, VCE=-3V
*hFE1	1	-	-	K	IC=-0.5A, VCE=-3V
*hFE2	1	-	-	K	IC=-3A, VCE=-3V

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



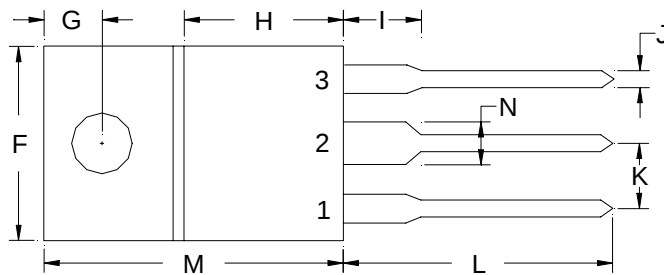
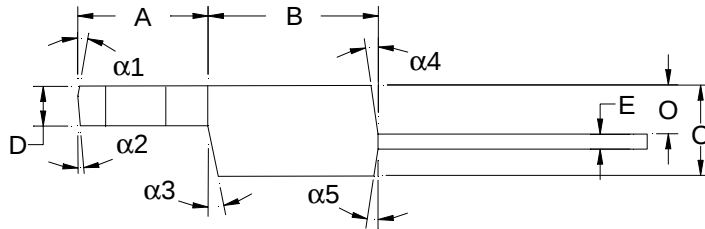


Characteristics Curve



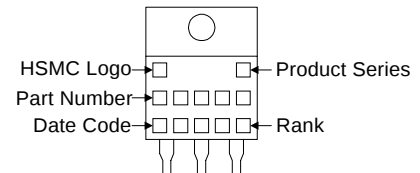


TO-220FP Dimension



3-Lead TO-220FP Plastic Package
HSMC Package Code : F

Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2480	0.2520	6.30	6.40	K	-	*0.1004	-	*2.55
B	0.3386	0.3425	8.60	8.70	L	0.5118	0.5906	13.00	15.00
C	0.1673	0.1870	4.25	4.75	M	0.5886	0.5925	14.95	15.05
D	0.1043	0.1083	2.65	2.75	N	-	*0.0669	-	*1.70
E	0.0230	0.0242	0.58	0.61	O	0.1098	0.1114	2.79	2.83
F	0.3980	0.4039	10.11	10.26	1	-	-2°	-	*2°
G	0.1083	0.1122	2.75	2.85	2	-	*5°	-	*5°
H	0.3386	0.3425	8.60	8.70	3	-	*15°	-	*15°
I	-	*0.1496	-	*3.80	4	-	*5°	-	*5°
J	-	*0.0236	-	*0.60	5	-	*5°	-	*5°

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel : 886-3-5983621~5 Fax : 886-3-5982931
- **Factory 2** : No. 17-1, Ta-Tung Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel : 886-3-5977061 Fax : 886-3-5979220